

# TT electronics: Bond With The Best

**Silicon Substrate:** These silicon chips provide designers with a wider selection of compact, yet extremely stable resistor solutions.

**Ceramic Substrate:** IRC now offers precision, moisture-resistant TaNFilm® technology in ceramic-based wire bondable resistors.

## TaNFilm® silicon and ceramic wire bondable resistor/capacitor chips from TT electronics

TT electronics now provides its proven tantalum nitride thin film technology in ultra-miniature silicon or ceramic-based wire bondable die, offering space savings, precision and reliability that thick film chips can't match— at prices that keep your designs competitive.

- Single chips, center-tapped dual chips, networks and capacitors with multiple pads for wire bonding
- Resistor chips at 20 mil square; two-resistor networks at 30 mil square with six pads for shortest available wire bonds
- Resistance values from 10 $\Omega$  to 400K $\Omega$ ; tolerances to  $\pm 0.1\%$ , TCR tracking to  $\pm 2\text{ppm}/^\circ\text{C}$
- Capacitors at 60 mil square with values from 10 to 1,000pF.
- Aluminum or gold wire bond pads standard; custom sizes, values and pad layouts also available
- Custom network configurations available - contact factory for our Wire Bondable Chip Catalog

Let TT electronics solve your hybrid circuit design challenges – specify wire bondable silicon and ceramic resistor die:

**Call Semi Dice, Inc. 562-594-4631**  
(an authorized distributor for WBC Series product.)



A Subsidiary of TT electronics plc

**IRC Advanced Film Division**  
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TT electronics Components Division manufactures a comprehensive range of electronic components, hybrids, sensors and assemblies.